



Material Content Data Sheet



Sales Product Name				IPB240N04S4-1R0		Issued		25. January 2018	
MA#				MA000998406					
Package				PG-TO263-7-3		Weight*		1539.62 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.981	0.52	0.52	5184	5184	
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521		
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156		
	non noble metal	copper	7440-50-8	801.714	52.05	52.12	520724	521401	
wire	non noble metal	aluminium	7429-90-5	20.750	1.35	1.35	13478	13478	
encapsulation	organic material	carbon black	1333-86-4	8.568	0.56		5565		
	plastics	epoxy resin	-	94.246	6.12		61214		
	inorganic material	silicondioxide	60676-86-0	468.374	30.42	37.10	304214	370993	
leadfinish	non noble metal	tin	7440-31-5	24.633	1.60	1.60	16000	16000	
plating	non noble metal	nickel	7440-02-0	0.539	0.04		350		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.04	1	351	
solder	noble metal	silver	7440-22-4	0.135	0.01		88		
	non noble metal	tin	7440-31-5	0.108	0.01		70		
	non noble metal	lead	7439-92-1	5.175	0.34	0.36	3361	3519	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	copper	7440-50-8	106.210	6.90	6.91	68984	69074	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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